Variant/Label Table

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>ChangeMe!</td>
</tr>
<tr>
<td>002</td>
<td>ChangeMe!</td>
</tr>
</tbody>
</table>

Assembly Notes:

*ZZ1*
- Assembly Notes
- Not necessary for BOM, but necessary for PCB labels only

*ZZ2*
- Assembly Notes
- These assemblies are ESD sensitive; ESD precautions shall be observed.

*ZZ3*
- Assembly Notes
- These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

*ZZ4*
- Assembly Notes
- These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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